

Semiquest Patent Listing as Understood by Pluritas

Although the Security Agreement defines the Assets, Pluritas understands these assets to include:

Country	Publication Number	Serial Number	Title	Status
United States of America		60/616944	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	Expired
United States of America	7846008	11/697622	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION AND CMP PAD	Granted
Patent Cooperation Treaty		US05/35979	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	National
China (People's Republic)	200580037158.5	2005 80037158.5	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	Granted
European Patent Convention		5808056.5	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	Abandoned
Japan		2007-535807	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	Pending
Korea, Republic of		2007-7010346	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	Pending
Taiwan	I270438	94135023	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	Granted
Singapore	131447	200702584-4	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION	Granted
United States of America		60/631187	CHEMICAL MECHANICAL PLANARIZATION PAD WITH PRESSURE CONTROL	Expired
Patent Cooperation Treaty		US05/35732	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION PAD WITH UNIFORM POLISH PERFORMANCE	Expired
United States of America		60/631188	CHEMICAL MECHANICAL PLANARIZATION PAD WITH UNIFORM POLISH	Expired
United States of America	8075745	11/576942	ELECTRO-METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION PAD WITH UNIFORM POLISH PERFORMANCE	Granted
Patent Cooperation Treaty		US05/35660	ELECTRO-METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION PAD WITH UNIFORM POLISH	National

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			PERFORMANCE	
United States of America		60/631189	ELECTRO-CHEMICAL MECHANICAL PLANARIZATION PAD WITH UNIFORM POLISH	Expired
Country	Publication Number	Serial Number	Title	Status
United States of America	7530880	11/576944	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION PAD WITH PRESSURE CONTROL AND PROCESS MONITOR	Granted
Patent Cooperation Treaty		US05/35978	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION PAD WITH PRESSURE CONTROL AND PROCESS MONITOR	National
Taiwan	1277484	94135795	METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION PAD WITH PRESSURE CONTROL AND PROCESS MONITOR	Granted
United States of America		60/636055	CHEMICAL MECHANICAL PLANARIZATION PAD WITH PROCESS MONITORING CAPABILITY	Expired
United States of America		60/639257	CHEMICAL MECHANICAL PLANARIZATION PAD WITH PAD WEAR INDICATOR	Expired
United States of America	7815778	11/562310	ELECTRO-CHEMICAL MECHANICAL PLANARIZATION PAD WITH UNIFORM POLISH PERFORMANCE	Granted
United States of America		11/562346	CHEMICAL MECHANICAL POLISHING PAD	Pending
United States of America		11/846304	POLISHING PAD AND METHOD OF USE	Abandoned
United States of America		13/162508	POLISHING PAD AND METHOD OF USE	Pending
Patent Cooperation Treaty		US08/73904	POLISHING PAD AND METHOD OF USE	National
China (People's Republic)		2008 80107121.9	POLISHING PAD AND METHOD OF USE	Pending
Korea, Republic of		10-2010-7006872	POLISHING PAD AND METHOD OF USE	Pending
Taiwan		97132950	POLISHING PAD AND METHOD OF USE	Pending
United States of America		60/969684	POLISHING PAD	Expired
United States of America	8066555	12/676318	POLISHING PAD	Granted
Patent Cooperation Treaty		US08/74658	POLISHING PAD	National
China (People's Republic)		2008 80107231.5	POLISHING PAD	Pending
Korea, Republic of		10-2010-7007067	POLISHING PAD	Pending
Taiwan		97133774	POLISHING PAD	Pending

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United States of America		11/968442	CHEMICAL MECHANICAL PLANARIZATION PAD AND METHOD OF USE THEREOF	Abandoned
United States of America		61/048785	POLISHING PAD AND METHOD OF USE	Expired
Country	Publication Number	Serial Number	Title	Status
United States of America		12/431119	POLISHING PAD AND METHOD OF USE	Pending
United States of America		61/048818	POLISHING PAD COMPOSITION	Expired
United States of America		12/141876	METHOD OF REMOVAL PROFILE MODULATION IN CMP PADS	Pending
United States of America		12/141907	METHOD AND APPARATUS FOR ASSEMBLY OF CMP POLISHING PADS	Abandoned
United States of America		61/111290	POLISHING PAD COMPOSITION	Expired
United States of America		12/431515	POLISHING PAD COMPOSITION AND METHOD OF MANUFACTURE AND USE	Pending
Patent Cooperation Treaty		US09/41944	POLISHING PAD COMPOSITION AND METHOD OF MANUFACTURE AND USE	National
China (People's Republic)		200980115576.X	POLISHING PAD COMPOSITION AND METHOD OF MANUFACTURE AND USE	Pending
European Patent Convention		9739577.6	POLISHING PAD COMPOSITION AND METHOD OF MANUFACTURE AND USE	Abandoned
Japan		2011-507575	POLISHING PAD COMPOSITION AND METHOD OF MANUFACTURE AND USE	Abandoned
Korea, Republic of		10-2010-7026820	POLISHING PAD COMPOSITION AND METHOD OF MANUFACTURE AND USE	Pending
Singapore		201007603-2	POLISHING PAD COMPOSITION AND METHOD OF MANUFACTURE AND USE	Pending
United States of America		61/111337	POLISHING PAD COMPOSITION	Expired
United States of America		61/118431	POLISHING PAD WITH ENDPOINT WINDOW AND SYSTEMS AND METHOD USING THE SAME	Expired
United States of America		12/616323	POLISHING PAD WITH ENDPOINT WINDOW AND SYSTEMS AND METHOD USING THE SAME	Pending
United States of America		12/991097*	POLISHING PAD WITH ENDPOINT WINDOW AND SYSTEMS AND METHOD USING THE SAME	Pending *Jointly Owned